

IMAPS ITALY WORKSHOP

Power Electronics for Sustainable Mobility

October 26th 2022

Politecnico of Milano – Bovisa

Sala Consiglio 0.09 - Building BL25

Via Raffaele Lambruschini 4, Milano



International Microelectronics
And Packaging Society
Italian Chapter

Programme

08:45 Registration

09:15 Welcome and Introduction

09:30 **Vehicles' Technological trends and challenges for a Sustainable Mobility**

Davide Tarsitano

Associate professor in Applied Mechanics, Politecnico di Milano - Milan, Italy

10:15 **Wide bandgap materials for power devices and power solutions**

Salvatore Coffa

Automotive&Discrete Group VP R&D General Manager

Power&Discrete technologies and products STMicroelectronics

11:00 Coffee Break

11:15 **Concepts for realizing High-Voltage Power Modules by Embedding of SiC Semiconductors**

Lars Boettcher

Fraunhofer Institute for Reliability and Microintegration (IZM) - Berlin, Germany

12:00 **ECPE Automotive Qualification Guideline AQG 324**

Leo Lorenz

Prof. Dr, President of ECPE European Center for Power Electronics e.V. - Germany

12:45 Lunch Break

14:00 **ECPE-Tutorial on 'Packaging of WBG Devices' Lifetime and Testing - 1st half**

Andreas Schletz

Head of Department Packaging & Reliability at Fraunhofer Institute IISB - Erlangen, Germany

15:45 Coffee break

16:00 **ECPE-Tutorial on 'Packaging of WBG Devices' 2nd half**

Power converter design from SiC bare dies – can we break the physical boundaries of power device package?

Teng Long, Professor University of Cambridge - UK

17.00 Conclusions

Information

The conference will be held in English in presence (maximum 100 people). Access is free subject to availability, mandatory registration at the following link:

<http://www.imaps-italy.it/news-eventi/in-primo-piano/26-october-2022-power-electronics-for-sustainable-mobility.html>

Contacts

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